

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Manufacturing fabrication process and wafer size changes (6-to-8 inch) - S12 to B12
Publication Date:	13-Mar-2023
Effectivity Date:	15-Jun-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	

Description Of Change:

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 Analog Devices products in current wafer fabrication process S12 (6-inch wafer size) at ADI's Beaverton/Oregon foundry (ADBN)

Reason For Change:

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 ADI is moving to the 8-inch B12 process to ensure adequate capacity for supply continuity.
 ADI has achieved equivalency between the two processes.
 ADI has been shipping products fabricated on the B12 Process in mass production from ADBN since 2009.
 The wafer fabrication location remains the same.

B12 process reliability qualification report is attached (ref. R060002FQ_B12_Qual)

The Form/Fit/Function of the devices is unchanged.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file